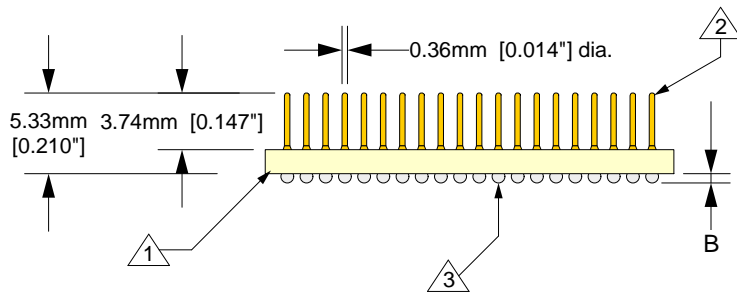


Top View
(reference only)

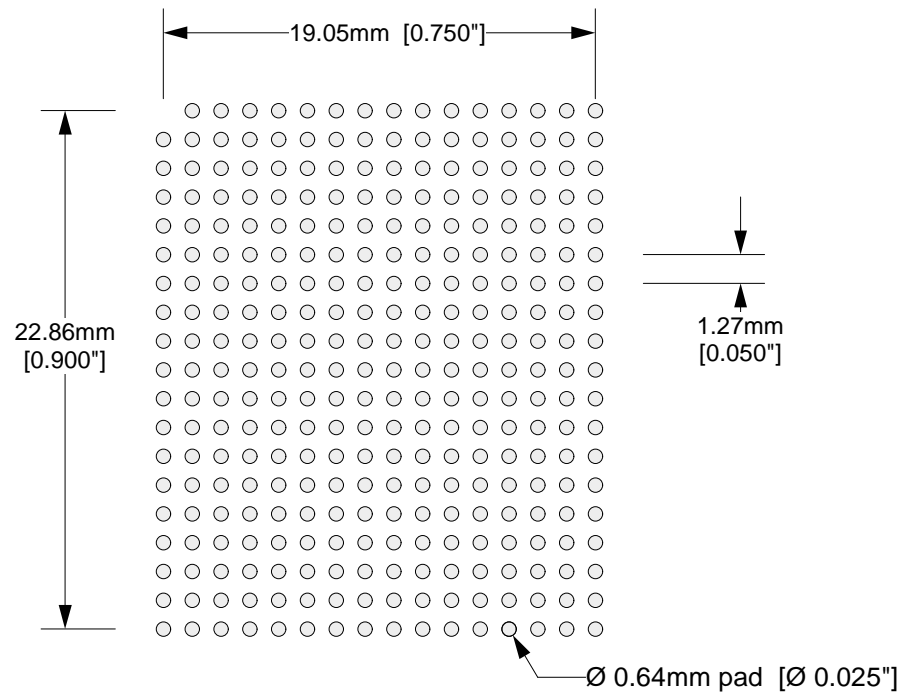


Side View
(reference only)

Note: SMT foot is independent of actual BGA package thickness.

- 1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. Non-clad.
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- 3 Balls: Eutectic 63/37 SnPb. Thermally isolated from terminal pins

Package Code: BGA303A




Top View: Recommended PCB Layout
Scale: 3:1

Pin Count	303
Array Size	16X19
Pitch	1.27mm[0.050"]
Perimeter size (XxY)	21.0mm[0.827"] x 25.0mm[0.984"]
MGA Location (CxD)	0.97mm[0.038"] x 1.07mm[0.042"]
Ball Thickness (B)	0.61mm[0.024"]

Description: BGA Emulator Foot (SM base).

303 position terminal pins (MGA, Mini-grid Array) to solder balls. Surface mounts to target BGA land pattern.

 <p>SF-BGA303A-B-11 Drawing</p> <p>© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Status: Released	Scale -	Rev: A
	Drawing: B. Roux		Date:10/21/04
	File: SF-BGA303A-B-11 Dwg.mcd		Modified:

Tolerances: diameters \pm 0.03mm [\pm 0.001"],
PCB perimeters \pm 0.13mm [\pm 0.005"],
PCB thicknesses \pm 0.18mm [\pm 0.007"],
pitches (from true position) \pm 0.08mm [\pm 0.003"],
all other tolerances \pm 0.13mm [\pm 0.005"]
unless stated otherwise. Materials and specifications are subject to change without notice.